## BAT54T/AD/CD/SD/BR

Taiwan Semiconductor

# 200mA, 30V Schottky Barrier Diode

### **FEATURES**

· Fast switching speed

TAIWAN

MICONDUCTOR

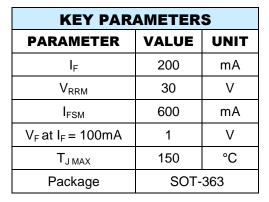
- Low forward voltage drop
- Surface mount device type
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- Voltage clamping
- Reverse polarity protection
- High speed switching

## **MECHANICAL DATA**

- Case: SOT-363
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Weight: 6.99mg (approximately)

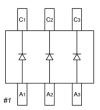


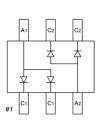


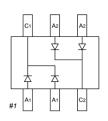
HALOGEN FREE

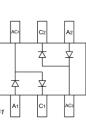


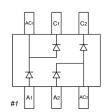
## **PIN CONFIGURATION**











BAT54T

BAT54AD

BAT54CD

BAT54SD

BAT54BR

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	BAT54 T	BAT54 AD	BAT54 CD	BAT54 SD	BAT54 BR	UNIT
Marking code on the device		KLA	KL6	KL7	KL8	KLB	
Power dissipation	P <sub>D</sub>	200 mV			mW		
Repetitive peak reverse voltage	V <sub>RRM</sub>	30			V		
Repetitive peak forward current	I <sub>FRM</sub>	300			mA		
Forward current	I <sub>F</sub>	200			mA		
Non-Repetitive peak forward surge current @ t < 1.0s	I <sub>FSM</sub>	600			mA		
Junction temperature range	TJ	-65 to +150			°C		
Storage temperature range	T <sub>STG</sub>	-65 to +150			°C		



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-ambient thermal resistance	R <sub>eja</sub>	625	°C/W		

PARAMETER	CONDITIONS		MIN	MAX	UNIT	
Forward voltage per diode <sup>(1)</sup>	$I_F = 0.1 \text{mA}, T_J = 25^{\circ}\text{C}$		-	0.24	V	
	$I_{\rm F} = 1 {\rm mA}, {\rm T}_{\rm J} = 25 {\rm °C}$		-	0.32	V	
	$I_F = 10 \text{mA}, T_J = 25^{\circ}\text{C}$	V <sub>F</sub>	-	0.40	V	
	$I_F = 30 \text{mA}, T_J = 25^{\circ}\text{C}$		-	0.50	V	
	I <sub>F</sub> = 100mA, T <sub>J</sub> = 25°C		-	1.00	V	
Reverse voltage	I <sub>R</sub> = 100μA, T <sub>J</sub> = 25°C	V <sub>R</sub>	30	-	V	
Reverse current @ rated $V_R$ per diode <sup>(2)</sup>	V <sub>R</sub> = 25 V, T <sub>J</sub> = 25°C	I <sub>R</sub>	-	2	μA	
Junction capacitance	1MHz, $V_R = 1V$	CT	-	10	pF	
$ \begin{array}{l} \mbox{Reverse recovery time} & I_F = I_R = 10 \mbox{mA} \ , \ R_L = 100 \Omega \ , \\ I_{RR} = 1 \mbox{mA} \end{array} , \  \  \  \  \  \  \  \  \  \  \  \  \$		t <sub>rr</sub>	-	5	ns	

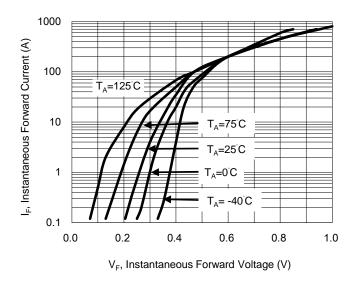
- Notes:
- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE	PACKAGE	PACKING		
BAT54T RFG	SOT-363	3K / 7" Reel		
BAT54AD RFG	SOT-363	3K / 7" Reel		
BAT54CD RFG	SOT-363	3K / 7" Reel		
BAT54SD RFG	SOT-363	3K / 7" Reel		
BAT54BR RFG	SOT-363	3K / 7" Reel		



### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)



**Fig.1 Typical Forward Characteristics** 

#### **Fig.2 Typical Reverse Characteristics**



#### Fig.3 Capacitance Between Terminals Characteristics

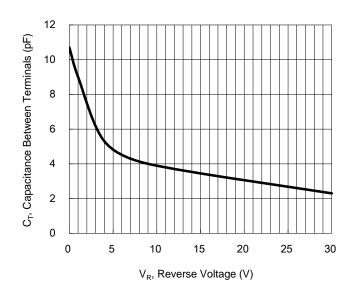
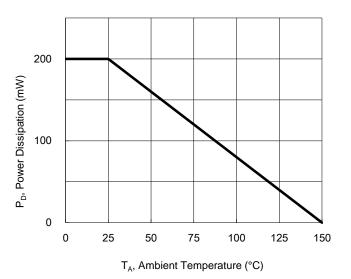


Fig.4 Power Derating Curve

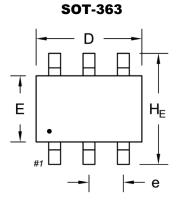


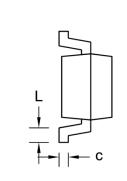


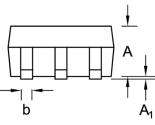
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### PACKAGE OUTLINE DIMENSIONS

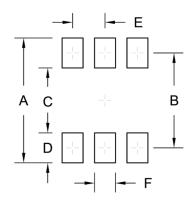






DIM.	J Unit (mm)		Unit (	(inch)
	Min.	Max.	Min.	Max.
A	0.90	1.00	0.035	0.039
A <sub>1</sub>	0.00	0.10	0.000	0.004
b	0.15	0.30	0.006	0.012
с	0.10	0.25	0.004	0.010
D	1.80	2.20	0.071	0.087
E	1.15	1.35	0.045	0.053
H <sub>E</sub>	2.00	2.20	0.079	0.087
е	0.65 (Ref.)		0.026 (Ref.)	
L	0.15	0.40	0.006	0.016

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.50	0.098
В	1.90	0.075
С	1.30	0.051
D	0.60	0.024
E	0.65	0.026
F	0.42	0.017

#### Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

#### MARKING DIAGRAM



= Marking Code



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